



Bill of Materials

TI DESIGNS

TIDA-00730 - IEC ESD Protected RS-485

Item	Qty	Reference	Value	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	C1	2.2uF	Any	Any (5V+ Rating)	1206
2	1	C2	1uF	Any	Any (5V+ Rating)	805
3	1	C3	0.1uF	Any	Any (5V+ Rating)	603
4	1	C4	10uf	Any	Any (5V+ Rating)	7343
5	1	C5	1uF	Any	Any (5V+ Rating)	402
6	3	C6,C7,R9	DNI	Any	Any (5V+ Rating)	603
7	1	D3	TVS	Bourns	CDSOT23-SM712	SOT_23_321
8	4	JMP1,JMP2,JMP5,JMP6	Header 3x1	Samtec	HTSW-150-08-G-S	berg1x3
9	2	JMP3,JMP4	Header 1x1	Samtec	HTSW-150-08-G-S	berg1x1
10	2	J1,J2, P1, P2	Solderless Banana Jack	Emerson Network Power Co	108-0740-001	JACK_THVT_BANANA_500DIA
11	6	R3,R4,R5,R6,R7,R8	49.9	Any	Any (1% Tolerance)	603
12	2	R10,R11	10	Any	Any (1% Tolerance)	603
13	1	U1	8D Half-Duplex	Texas Instruments	SN65HVD82	8Pin D

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